

Upcoming: April 1–2 Condensed Matter Workshop, MRS; April 4–8 2005 Intl. Magnetism Conf. (INTERMAG2005), Endorsed; April 11–14 Fourteenth Intl. Conf. on Microscopy of Semiconducting Materials, Endorsed.

To list an event in the Calendar, contact J. Meiksin, Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3004 ext. 522; fax 724-779-8313; bulletin@mrs.org.

MRS, A-MRS, B-MRS, C-MRS, E-MRS, MRS-A, MRS-I, MRS-J, MRS-K, MRS-R, MRS-S, MRS-T, M-MRS, or IUMRS at the end of an entry indicates sponsorship or co-sponsorship of an event by the International Union of Materials Research Societies or one of its adhering bodies. "Endorsed" identifies events endorsed by MRS.

▼ identifies a new or revised entry this month.

See the January 2005 MRS BULLETIN for March 2005 Calendar entries. For updates, access www.mrs.org/meetings/other/.

APRIL 2005

1–2 Condensed Matter Workshop, San Francisco, CA. Materials Research Society, Materials Research Society, 506 Keystone Drive, Warrendale, PA, 724-779-3003; fax 724-779-8313; e-mail info@mrs.org; www.mrs.org/meetings/workshops/2005/condensed_matter. **MRS.**

4–5 OPTO-Ireland 2005, Dublin, Ireland. SPIE, SPIE Meetings, P.O. Box 10, Bellingham, WA, 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; spie.org/conferences/calls/05/ire.

4–6 PM Asia—2005, Shanghai, China. Nick Williams, Inovar Event Management, Dogpole House, Shrewsbury, United Kingdom, 44-0-1743-241289; e-mail Nick@inovar-events.com; www.pmasia2005.com.

4–7 Government Microcircuit Applications & Critical Technology Conf. (GOMACTech), Las Vegas, NV. Kate Dickie, GOMACTech, 212-460-8090 x215; e-mail kdickie@pcm411.com; www.gomactech.net.

4–8 2005 Intl. Magnetism Conf. (INTERMAG2005), Nagoya, Japan. InterMag 2005 Secretariat, c/o Convention Linkage, Inc., Akasaka-Nihon Bldg., 9-5-24, Akasaka, Minato-ku, Tokyo 107-0052, Japan; 81-3-5770-5531; fax 81-3-5770-5532; e-mail info@intermag2005.jp; www.intermag2005.jp. **Endorsed.**

5–6 EmTech—Emerging Technologies for Drug Discovery Conf. and Exhibition, San Francisco, CA. Richard Sampson, 44-0-1787-315117; e-mail r.sampson@selectconferences.com; www.Emtech.biz.

5–7 SAMPE—Europe, Paris, France. e-mail registration@sampe.org; www.sampe.org.

11–13 The Intl. Conf. on Ceramic Interconnect and Ceramic Microsystems Technology, Westerville, OH. Ann Bell, IMAPS, 202-548-8717; e-mail abell@imaps.org; www.ceramics.org.

11–14 Fourteenth Intl. Conf. on Microscopy of Semiconducting Materials, Oxford, United Kingdom. Univ. of Sheffield, Tony Cullis, Sheffield, United Kingdom, 44-114-222-5407; fax 44-114-272-6391; e-mail a.g.cullis@sheffield.ac.uk; www.rms.org.uk. **Endorsed.**

17–20 ISIF—Intl. Symp. on Integrated Ferroelectrics, Shanghai, China. Kerry Baugh, University of Colorado at Colorado Springs, 1420 Austin Bluffs Pkwy, Colorado Springs, CO, 80933-7150; 719-598-2285; fax 719-594-4257; e-mail kerry@isif.net; www.isif.net.

24–28 15th Intl. Conf. on Wear of Materials, San Diego, CA. Gill Heaton, Secretariat, Hillside Cottages, Wheatley Road, Islip, Oxford OX5 2TF, UK; 44-0-1865-373625; fax 44-0-1865-375855; e-mail wom-conference@elsevier.com; www.wom-conference.elsevier.com.

25–30 Asia-Pacific Winter Conf. on Plasma Spectrochemistry, Chiang Mai, Thailand. Ramon Barnes, ICP Newsletter Information, Inc., P.O. Box 666, Hadley, MA, 01003-0666; 413-256-8942; fax 413-256-3746; e-mail wc2005@chem.umass.edu; www-unix.oit.umass.edu/~wc2005.

MAY 2005

1–5 SAMPE—Intl. Symp. and Exhibition, Long Beach, CA. e-mail registration@sampe.org; www.sampe.org.

8–10 Meeting on Society of Nano Science and Technology, Sendai, Japan. Yukiko Miyahara, Tohoku University, 2-1-1 Katahira Aoba-ku, Sendai, Japan, 81-22-215-2054; fax 81-22-215-2052; e-mail nano2005@imr.edu; www.nano2005.imr.edu/english_index.html.

10–11 RAPRA—Blowing Agents & Foaming Processes 2005, Stuttgart, Germany. Rapra Technology Limited, Shawbury, Shrewsbury, SY4 4NR, United Kingdom, 44-0-1939-250383; fax 44-0-1939-251118; e-mail conferences@rapra.net; www.polymerconferences.com.

15–20 ECS—Electrochemical Society Meeting, Quebec City, Canada. The Electrochemical Society, 65 S. Main Street, Building D, Pennington, NJ, 08534-2839; 609-737-1092; fax 609-737-2743; e-mail ecs@electrochem.org; www.electrochem.org.

29–3 2nd Intl. Conf. on Electrophoretic Deposition: Fundamentals and Applications, Barga, Italy. Impe. C. of Sci, Tech. & Med., A. Boccaccini, London, United Kingdom, 44-207-5946731; fax 44-207-5843194; e-mail a.boccaccini@imperial.ac.uk; www.engconfintl.org/5ad.html.

29–3 Solid-Solid Phase Transformations in Inorganic Materials 2005, Phoenix, Arizona. TMS Meeting Services, 184 Thorn Hill Road, Warrendale, PA 15086 USA; 724-776-9000, ext. 243; e-mail mtgserv@tms.org; www.tms.org/meetings/specialty/ptm/home.html. **Endorsed.**

31–3 2005 E-MRS Spring Meeting, Strasbourg, France. Paul Siffert, General Secretary, European Materials Research Society Headquarters, BP 20, 67037 Strasbourg Cedex 2, France; 33-3-88-106273; fax 33-3-88-106343; e-mail emrs@phase.c-strasbourg.fr; www-emrs.c-strasbourg.fr. **E-MRS.**

31–3 ISM—Intl. Symp. on Metallomesogens, Lake Arrowhead, CA. Gerald Van Hecke, Harvey Mudd College, 301 East Twelfth Street, P.O. Box 5990, Claremont, CA, 91711; 909-607-3935; fax 909-607-7577; e-mail gerald_vanhecke@hmc.edu; ism05.sewanee.edu. **Endorsed.**

JUNE 2005

7–10 Intl. Conf. on Advances in Solidification Processes (ASP), Stockholm, Sweden. KTH Casting of Metals, ASP, S-100 44, Stockholm, Sweden, 46-8-790-6654; fax 46-8-21-65-57; e-mail asp@matpr.kth.se; www.webforum.com/solidificationprocessing. **E-MRS.**

8–11 PLMCM—Intl. Conf. on Physics of Light-Matter Coupling in Nanostructures, Glasgow, United Kingdom. e-mail plmcm5@phys.strath.ac.uk; plmcm5.phys.strath.ac.uk.

9–11 China Intl. Conf. on Nanoscience and Technology (ChinaNano2005), Beijing, Peoples Republic of China. e-mail chinanano@nanocr.cn; www.chinanano2005.org.

12–17 ECS—Intl. Conf. on Polymer Batteries and Fuel Cells (PBFC), Las Vegas, NV. The Electrochemical Society, 65 S. Main Street, Building D, Pennington, NJ, 08534-2839; 609-737-1092; fax 609-737-2743; e-mail ecs@electrochem.org; www.electrochem.org.

13–15 Intl. Coatings, Paintings and Anti-Corrosion Expo, Beijing, China. Andrea Hilligardt, Mesago Holding Operations GmbH, Rotebuehlstr. 87, D-70178 Stuttgart, Germany, 49-711-490-890-23; fax 49-711-490-890-10; e-mail a.hilligardt@intercoat.china.com; www.china-intercoating.com.

14–17 ICOMAT—Intl. Conf. on Martensitic Transformation, Shanghai, China. e-mail icomat@sjtu.edu.cn; www.icomat.sjtu.edu.cn.

19–23 Intl. Congress on Thin Films and Intl. Conf. on Atomically Controlled Surfaces, Interfaces, and Nanostructures, Stockholm, Sweden. Congrex Sweden AB, P.O. Box 5619, SE-114 86, Stockholm, Sweden, 46-8-459-66-00; fax 46-8-661-91-25; e-mail acsin8@congrex.se; www.congrex.com/acsin8.

20–22 ISPAC: Intl. Symp. on Polymer Analysis and Characterization, Sheffield, United Kingdom. University of Sheffield, Shelagh Cowley, Dainton Building, Brook Hill, Sheffield, United Kingdom, 44(0)114-222-9537; fax 44(0)114-222-9389; e-mail s.h.cowley@sheffield.ac.uk; www.chem.cmu.edu/ispac.

26–30 17th University Conf. on Glass Science, University Park, PA. Donna Lucas, Materials Research Institute—Penn State University, 280 Materials Research Laboratory Building, University Park, PA 16802, 814-865-1656; fax 814-865-2326; e-mail dzm4@psu.edu; www.mri.psu.edu/conferences/glass-science/.

JULY 2005

3–8 Intl. Conf. on Materials for Advanced Technologies (ICMAT 2005) and IUMRS-ICAM 2005, Singapore. Mat Research Soc (Singapore), ICMAT Secretariat, 3 Research Link, Singapore, 65-6874-1975; fax 65-6777-2393; e-mail icmat@mrs.org.sg; www.mrs.org.sg/meeting_future.html. **IUMRS/MRS-S.**

3–8 Intl. Conf. on Scanning Tunneling Microscopy/Spectroscopy and Related Techniques (STM) with the Intl. Colloquium on Scanning Probe Microscopy (ICSPM), Sapporo, Japan. Hokkaido University, Takaharu Okajima, Kita-ku N21 W10, Sapporo, Japan, 81-0-11-706-9341; fax 81-0-11-706-9355; e-mail stm05@es.hokudai.ac.jp; dora.ims.tsukuba.ac.jp/event/STM05/index.html.

4–8 Lucerne Fuel Cell Forum 2005, Lucerne, Switzerland. EFCF, Morgenacherstrasse 2F, P.O. Box 99, Oberrohrdorf, Switzerland, 41-56-496-7292; fax 41-56-496-441; e-mail forum@efcf.com.

6–8 Intl. Conf. on Diffusion in Solids and Liquids (DSL-2005), Aveiro, Portugal. University of Aveiro, Dept. of Mechanical Engineering, Campus Universitario de Santiago, Aveiro, Portugal, 351-234-378162; fax 351-234-370953; e-mail DSL-2005@mec.ua.pt; event.ua.pt/dsl2005.

10–13 Organic Microelectronics Workshop, Newport, RI. 202-872-4600 or 1-800-227-5558; e-mail acsprospectives@acs.org; www.mrs.org/meetings/workshops/2005/organic_microelectronics. **MRS.**

10–15 16th Intl. Conf. on Electronic Properties of Two-Dimensional Systems (EP2DS-16), Albuquerque, NM. Jerry Simmons, 505-844-8402; e-mail jsimmon@sandia.gov. **Endorsed.**

17–22 Intl. Conf. on Solid State Ionics (SSI-15), Baden-Baden, Germany. Ellen Ivers-Tiffée, c/o Universität Karlsruhe, Kaiserstr. 12, D-76131 Karlsruhe, Germany; 49-721-608-7491; fax 49-721-608-7492; e-mail info@ssi-15.net; www.ssi-15.net.

19–23 5th Intl. Conf. on Intelligent Processing and Manufacturing of Materials, Monterey, CA. IPMM 05, www.mining.ubc.ca/ipmm.

AUGUST 2005

21–25 IMRC—Intl. Materials Research Congress, Cancun, Mexico. Ventura Rodriguez Lugo, 29 Oriente 601-1, Col Ladrillera De Benitez, Puebla, Mexico, 52-222-211-4393; fax 52-222-211-4393; e-mail lugo.ventura@cuv.buap.mx; www.viep.buap.mx/imrc2005.htm.

28–2 6th Intl. Conf. on Nitride Semiconductors (ICNS-6), Bremen, Germany. Sven Einfeldt, University of Bremen, P.O. Box 330440, Bremen, Germany; 49-421-218-7453; fax 49-421-218-4581; e-mail icns6@ifp.uni-bremen.de; www.ifp.uni-bremen.de/icns6.

30-2 ECSSC X 2005 European Conf. on Solid State Chemistry, *Sheffield, United Kingdom*. Louise Draycott, University of Sheffield, Sir Robert Hadfield Building, Mappin Street, Sheffield, United Kingdom, 44-0-114-222-60-27; fax 44-0-114-222-59-43; e-mail L.Draycott@sheffield.ac.uk; www.shef.ac.uk/materials/ecssc.

SEPTEMBER 2005

4-9 ▼ SMMIB—Intl. Conf. on Surface Modification of Materials by Ion Beams, *Kusadasi, Turkey*. Conference Secretary SMMIB, 90-232-343-44-00; fax 90-232-374-42-89; e-mail info@smmib05.net; www.smmib05.net. **Endorsed.**

7-9 ▼ ICSCnanoSMat—Intl. Conf. on Surfaces Coatings and Nanostructured Materials, *Aveiro, Portugal*. Sabrina Morais, University of Aveiro, 3810-193 Aveiro, Portugal, 351-234-378-177; fax 351-234-370-953; e-mail ICSCNM@mec.ua.pt; www.mec.ua.pt/ICSCNM.

12-16 ▼ ECI—Micromechanics and Microstructure Evolution: Modeling, Simulation and Experiments, *Madrid, Spain*. ECI, 6 Metro Tech Center, Brooklyn, NY, 11201; 718-260-3743; fax 718-260-3754; e-mail info@eci.poly.edu; www.engconfintl.org/5as.html.

12-16 European Solid-State Device Research Conf. (ESSDERC), *Grenoble, France*. Iris Mazure, 46 Avenue Felix Viallet, Grenoble Cedex, France, 33-476-57-49-89; fax 33-476-47-38-14; e-mail esscirc-essderc@imag.fr; www.essderc2005.com.

OCTOBER 2005

2-5 3rd Fracture and Flow in Advanced Glasses Conf., *University Park, PA*. Carlo Pantano; ars2@psu.edu.

6-7 ▼ IACC—Intl. Activated Carbon Conf., *Pittsburgh, PA*. Henry Nowicki, PACS Testing and Consulting, 409 Meade Drive, Coraopolis, PA, 15108; 724-457-6576; fax 724-457-1214; e-mail hnpacks@aol.com; www.pacslabs.com.

9-14 ECI—Instrumented Indentation Testing in Materials Research and Development, *Crete, Greece*. E-mail info@eci.poly.edu; www.engconfintl.org/5av.html.

12-16 ▼ AIOM—Advances in Optical Materials, *Tucson, AZ*. Sophie Peters AIOM Conference Secretariat, Elsevier, The Boulevard, Langford Lane, Kidlington, Oxford OX5 1GB, United Kingdom, 44-0-1865-843643; fax 44-0-1865-843958; e-mail s.peters@elsevier.com; www.aiom.elsevier.com.

16-21 ▼ ECS—Electrochemical Society Meeting, *Los Angeles, CA*. The Electrochemical Society, 65 S. Main Street, Building D, Pennington, NJ, 08534-2839; 609-737-1092; fax 609-737-2743; e-mail ecs@electrochem.org; www.electrochem.org.

17-21 ASNT Fall Conf. and Quality Testing Show 2005, *Columbus, OH*. Kelly Thomas, American Society for Nondestructive Testing, P.O. Box 28518, 1711 Arlington Ln, Columbus, OH 43228-0518; 800-222-2768 x227; fax 614-274-6899; kthomas@asnt.org; www.asnt.org.

NOVEMBER 2005

14-16 Continuous Casting of Non-Ferrous Metals Intl. Conf. & Exhibition, *Neu-Ulm, Germany*. Vera Hausen, Niels Parusel, DGM Secretariat, Deutsche Gesellschaft für Materialkunde, Hamburger Allee 26, Frankfurt, Germany, 49-69-7917-747; fax 49-69-7917-733; e-mail concast@dgm.de; www.dgm.de/concast.

22-25 Ninth NCB Intl. Seminar on Cement, *New Delhi, India*. NCCBM, Ninth NCB, 34 Km Stone, Delhi Mathura Road (NH2), Ballabgarh 121 004, Haryana, India, 91-129-2242051-56; fax 91-129-2242100, 2246175; e-mail nccbm@giasd101.vsnl.net.in.

29-3 MRS Fall Meeting, *Boston, MA*. Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; e-mail info@mrs.org; www.mrs.org. **MRS.**

DECEMBER 2005

4-9 Intl. Conf. on Fusion Reactor Materials, *Santa Barbara, CA*. R.J. Kurtz, e-mail icfrm-tp@engineering.ucsb.edu; icfrm-12.pnl.gov/index.stm.

5-7 2nd Intl. Conf. on Advances in Production and Processing of Aluminum (APPA 2005), *Bahrain*. Conf. Secretariat (APPA 2005), Univ. of Bahrain, P.O. Box 32038, Bahrain, 973-17876114; fax 973-17876655; e-mail appa2005@eng.uob.bh; www.uob.edu.bh/colleges/engineering/conf/index.htm.

AUGUST 2006

27-31 TMS—Sohn Intl. Symp. on Advanced Materials: Principles, Technologies, and Industrial Practice, *San Diego, CA*. TMS Meetings Services, 184 Thorn Hill Road, Warrendale, PA, 15086; 724-776-9000 x243; fax 724-776-3770; e-mail mtgserv@tms.org; www.tms.org/Meetings/Specialty/FallExt2006/FallExt2006-Home.html. **Endorsed.** □

Advanced Metallization Conference (AMC) 2005

September 27-29, 2005, in Colorado Springs, Colorado

Announcement and Call for Papers

This conference is the 22nd in a series devoted to leading-edge research in the field of advanced metallization and 3-D integration for IC applications. PAPERS ARE SOLICITED on topics affecting state-of-the-art and future directions in interconnect systems, including:

Metallization science and interfaces

Advanced deposition techniques and kinetics
Nucleation and adhesion studies
Diffusion barrier performance

Interconnect thin film microcharacterization

Electrical and mechanical properties
Morphology evolution and stability

Advanced semiconductor device architecture

Low-k dielectrics
Metal and dielectric thin film barriers
High-k and ferroelectric capacitors
Inductors, capacitors, etc., in the wiring levels
Advanced wiring schemes (e.g., for embedded DRAM, system-on-a-chip, etc.)

Vertical (3-D) interconnects

Nano-interconnects
Metal gate transistors design, fabrication, characterization, and reliability

RF interconnects

Interaction of packaging with on-chip interconnects

Process modeling

Advancements in CVD and PVD deposition
Electrochemical and electroless deposition
Chemical mechanical polishing
Novel deposition and planarization techniques

Multilevel process integration issues

System-on-a-chip
3-D system integration
Novel interconnect system concepts
Chip interconnect/packaging interface issues
MEMS metallization issues and solutions
Advanced patterning and etching processes
Damascene and dual-damascene techniques
Barrier/liner/fill technology
Integration of Cu and Al with low-k dielectrics

Reliability and performance data and simulations

Dual damascene process defects
Electromigration and stress migration
Dielectric reliability and diffusion studies
Adhesion, corrosion, and other stress testing
Reliability of active chips with Cu and/or low-k
Bonding and packaging issues for advanced interconnects

Abstracts are due May 23, 2005.

Send abstracts (two pages, 500 words, with supporting figures on second page) to Jenny Black Deer, UC Berkeley Extension, 1995 University Ave., Berkeley, CA 94720-7010; fax: (510) 642-6027; e-mail: amc@unex.berkeley.edu. Please note: all abstracts submitted electronically must be a pdf file (all fonts must be embedded in the file). Include the author's name, affiliation, mailing address, e-mail address, and phone and fax numbers on the abstract.

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